

**ABSTRACT OF THE DISCLOSURE**

A method for fabrication of microelectromechanical systems (MEMS) .  
integrated micro devices and acceleration sensor devices formed according to the method, the  
method being micromachining an array of first three-dimensional micromechanical device  
5 features in a first silicon wafer; micromachining an array of second three-dimensional  
micromechanical device features in a second silicon wafer, wherein the second  
three-dimensional micromechanical device features are configured to cooperate with the first  
three-dimensional micromechanical device features when joined therewith; mutually aligning  
the first and second arrays of device features by aligning the first and second wafers;  
10 permanently joining the first and second arrays of device features into an array of integrated  
micro devices as a function of permanently joining the first and second wafers into a single  
composite wafer; and subsequently separating the array of integral devices into individual  
devices each having a set of the first and second device features.